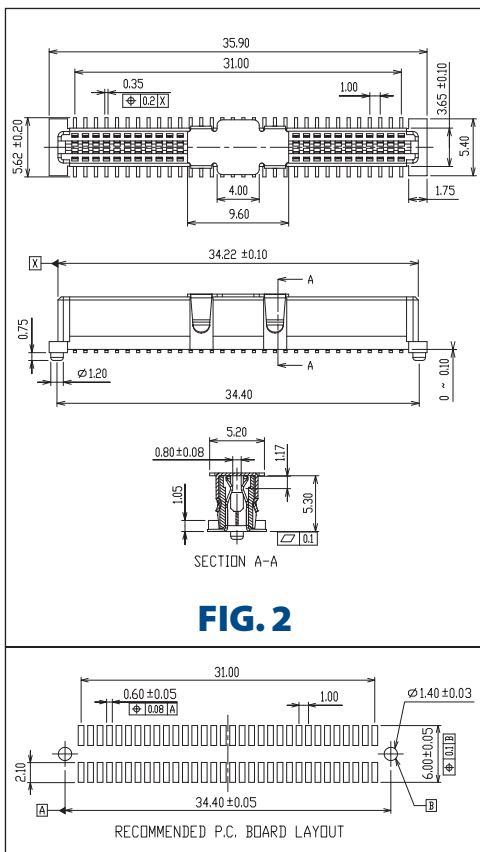
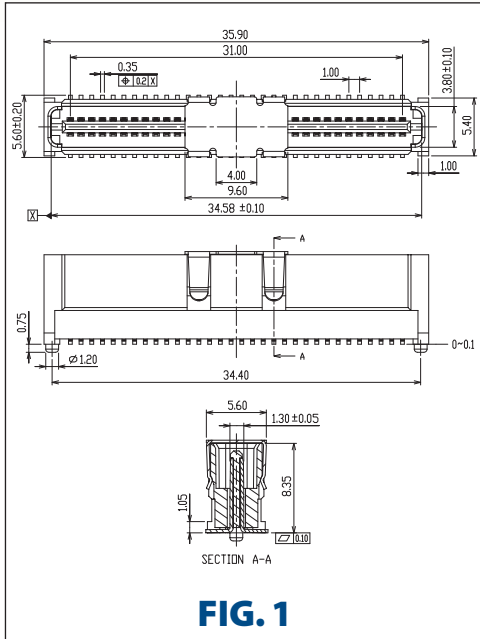
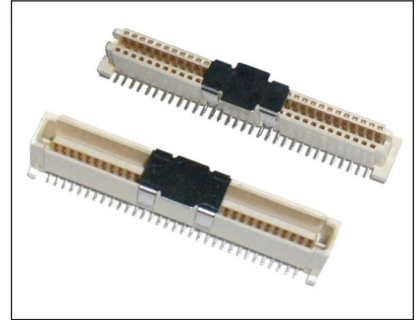


# INTERCONNECTS

## SERIES 891 & 893 • 1 mm GRID SURFACE MOUNT • MALE AND FEMALE CONNECTORS



- 64 Position Mezzanine Connectors for board stacking
- 1 mm Centerline high density packaging
- Mated connector board stacking height of 10 mm
- Conforms to EIA-700 AAAB for IEEE 1386 applications
- Tape & Reel packaged per EIA-783 (56 mm wide; 16 mm pitch)
- Insulators are high temperature thermoplastic, suitable for all soldering operations



### ORDERING INFORMATION

<b>FIG. 1</b>	<b>Series 891...120 1mm Surface Mount Male Connector</b>
	891-10-064-30-120000 <b>Tape and Reel Packaging:</b> 400 Parts per 330mm reel
<b>FIG. 2</b>	<b>Series 893...420 1mm Surface Mount Female Connector</b>
	893-43-064-30-420000 <b>Tape and Reel Packaging:</b> 600 Parts per 330mm reel

### Technical Specifications

#### Materials:

Terminals and Contacts: Phosphor Bronze  
 Plating: Contact area - 0,76µm Gold over Nickel  
 Solder Terminals - 1,9µm Tin over Nickel  
 Vacuum Cap: Stainless Steel  
 Insulator Material: High temperature glass filled LCP, rated UL 94V-0



#### Ratings:

Current: (30° C Temperature Rise): 0.5 A max., all circuits wired in series (1.0A max., five adjacent circuits wired in series)  
 Voltage: 250V AC (RMS) (contact to contact)  
 Operating Temperature Range: -55° C - +85° C

#### Electrical:

Contact resistance: 30mΩ max.  
 Insulation resistance: 1,000 MΩ min.  
 Dielectric Withstanding Voltage: 250V AC for one minute @ sea level

#### Mechanical:

Vibration: No discontinuity > 1 ms per MIL-STD 202, Method 201  
 Physical Shock: No discontinuity > 1 µs per EIA 364-27 Test Condition H  
 Durability: 100 cycles min. per EIA 364-09  
 Mating Force: 60 g/terminal max. per EIA 364-13  
 Separation Force: 23 g/terminal min. per EIA 364-13  
 Contact Retention Force: .4Kg min. per EIA 364-35

#### Environmental:

Thermal Shock: Per EIA 364-32, Test Condition I  
 Humidity: Test conditions - Ambient temp. 40±2°C; Relative humidity: 90 - 95%; Duration: 96 Hrs.  
 Post Humidity Inspection - 1. No damage  
 2. Contact resistance change < 15 mΩ  
 3. Insulation Resistance: 100 MΩ min.  
 Solderability: Per EIA 364-52 Category 2

